



## XSON

MSL Level

HAST

Pressure Cook Test

**Temperature Cycling** 

High Temperature Storage

Extremely Small Outline No Lead Package

	SPECIFICATIONS
Gold Wire	99.99% Au
Mold Compound	G770 (Green)
Plating	Matte Tin
Marking	Laser Mark
Packing	Antistatic Tube or Tray

plastic encapsulated package with exterior leads around the bottom periphery of the package to provide short electrical connection to the PWB. The package also provides excellent thermal performance by having the die attach paddle exposed on the bottom of the package surface to provide efficient heat path when soldering directly to the PWB.

DESCRIPTION

Lingsen Quad Flat No-lead (QFN) package is a

### APPLICATIONS

Telecommunication Products, Cellular Phone
Wireless LAN

• Low to medium lead count packages Information appliances

 Portable Products, PDA, Digital Camera, MP3 player, Pagers

#### **FEATURES**

- Reduce electrical parasitic
- Driven by high frequency for telecom
- Lower thermal resistance
- Improved board space efficiency
- Reduced mounted height
- Reduced package mass (Handsets , PDAs)

DEFINITION

RELIABILITY

JEDEC Level 3 @ 260°C

168 hrs (121°C,100%RH, 2atm

1,000 cycles (-65°C/+150°C)

100 hrs (130°C, 85%RH)

1,000 hrs (150°C)

• QFN (Quad Flat No-lead Package):

Exterior leads are around the bottom periphery of the package

Temperature & Humidity Test 1,000 hrs (85°C, 85%RH)

• SON (Small Outline No-lead Package) :

Exterior leads are only in the bottom dual side of the package

- V type: Package thickness is 0.9 mm
- W type: Package thickness is 0.75 mm
- U type : Package thickness is 0.55 mm

THERMAL PERFORMANCE								
Package	Body Size (mm)	Pad Size (mm)	Die Size (mm)	Thermal Performance <sup></sup> ∂ja (°C/W)				
VQFN 16L	4x4	2.45x2.45	1.872x1.9545x0.36	26.4				
VQFN 48L	7x7	5.40x5.40	2.5x4.0x0.2286	10.1				

Note: Simulated with JEDEC Standard 4-layer test board under still air condition, ambient temperature 45°C

	ELECTRICAL PERFORMANCE									
Package	Body Size (mm)	Pad Size (mm)	Frequency (MHz)	Self Inductance (nH)	Self Capacitance (pF)	Resistance (mohm)				
VQFN 16L	4x4	2.45x2.45	100	0.5893~0.8255	0.1370~0.1583	48.13~169.9				
VQFN 48L	7x7	5.40x5.40	100	1.0840~2.4560	0.1605~0.2113	133.6~448.8				

Note: Results are simulated. Data is available through 100 MHz.

# CROSS-SECTION Lead Frame Gold Wire Die